


APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention	CHIP STRUCTURE WITH BUMPS AND A PROCESS FOR FABRICATING THE SAME		
Application Type : regular, utility Attorney Docket Number : 8012-US-PA-1			
Correspondence address: Customer Number: 31561 			
Continuing Data: This is a Division of US application number 10065632, filed 2002-11-05 , now pending.			
Priority Data: Doc.No: 91100094; Country -TW ; Date: 2002-01-07 us-priority-claimed			
Inventor Information: <u>Inventor 1:</u> Applicant Authority Type: Inventor Citizenship: TW Name prefix: Mr. Given Name: Chao-Fu Family Name: Weng Residence: City of Residence: Tainan Country of Residence: TW Address-1 of Mailing Address: No. 19-3, Lane 19, Hsinchien Rd Address-2 of Mailing Address: City of Mailing Address: Tainan State of Mailing Address: Postal Code of Mailing Address: Country of Mailing Address: TW Phone: Fax: E-mail:			

Attorney Information:

practitioner(s) at Customer Number:

31561



as my attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.